



INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

# **IEC/TC107: Process management for avionics**

**Working Group 1 Report to TC107 Plenary  
meeting**

**-- 12 Oct. 2012 --**

***Working Group (WG 1)***

## **WG 1 activities since the last TC107 Plenary (Oct. 2011) and for the next months/years**

- **Project/Document IEC/TS 62647-2      *Process management for avionics-aerospace and defence electronic systems containing lead-free solder – part 2: Mitigation of deleterious effects of tin***
  - **Status IEC/TS 62647-2**
    - *Respond to the comments on the questionnaire provided by Stephanie Archard*
  - **IEC/TS 62647-2 Program of Work (PoW) for the next months / years**
    - *Change the forecasted publication date from January 2013 to May 2013*
    - *WG 1 will complete a final review of the document to ensure all the WG 1 comments have been properly addressed then submit the IEC/TS 62647-2 for publication*

## **WG 1 activities since the last TC107 Plenary (Oct. 2011) and for the next months/years (continued)**

- **Project/Document IEC/TS 62647-3      *Process management for avionics-aerospace and defence electronic systems containing lead-free solder – part 3: Performance testing for systems containing lead free solder and finishes***
  - **Status IEC/TS 62647-3**
    - *Next stage is DTS*
  - **IEC/TS 62647-3 Program of Work (PoW) for the next months / years**
    - *Change the forecasted next stage date from April 2012 to March 2013*
    - *WG 1 will complete a final review of the document to ensure all the WG 1 comments have been properly addressed then submit the IEC/TS 62647-3 as DTS*

## **WG 1 activities since the last TC107 Plenary (Oct. 2011) and for the next months/years (continued)**

- **Project/Document IEC/TS 62647-21      *Process management for avionics-aerospace and defence electronic systems containing lead-free solder – Part 21: Program management - Systems engineering guidelines for managing the transition to lead-free electronics***
  - **Status IEC/TS 62647-21**
    - *The next stage is DTS*
  - **IEC/TS 62647-21 Program of Work (PoW) for the next months / years**
    - *Change the forecasted next stage date from October 2012 to March 2013*
    - *WG 1 will complete a final review of the document to ensure all the WG 1 comments have been properly addressed then submit the IEC/TS 62647-21 as DTS*

## **WG 1 activities since the last TC107 Plenary (Oct. 2011) and for the next months/years (continued)**

- **Project/Document IEC/TS 62647-22      *Process management for avionics-aerospace and defence electronic systems containing lead-free solder – Part 22: Technical guidelines***
  - **Status IEC/TS 62647-22**
    - *The next stage is DTS*
  - **IEC/TS 62647-22 Program of Work (PoW) for the next months / years**
    - *Change the forecasted next stage date from October 2012 to March 2013*
    - *WG 1 will complete a final review of the document to ensure all the WG 1 comments have been properly addressed then submit the IEC/TS 62647-22 as DTS*

## **WG 1 activities since the last TC107 Plenary (Oct. 2011) and for the next months/years (continued)**

- **Project/Document IEC/TS 62647-23      *Process management for avionics-aerospace and defence electronic systems containing lead-free solder – Part 23: Rework and repair guidance to address the implications of lead-free electronics and mixed assemblies***
  - **Status IEC/TS 62647-23**
    - *The next stage is DTS*
  - **IEC/TS 62647-23 Program of Work (PoW) for the next months / years**
    - *Change the forecasted next stage date from October 2012 to March 2013*
    - *WG 1 will complete a final review of the document to ensure all the WG 1 comments have been properly addressed then submit the IEC/TS 62647-23 as DTS*

## Decisions requested from TC107 Plenary Oct. 2012

- **Decision request 1**      *N/A*

## Other topics submitted to TC107 Plenary Oct. 2012:

- **GEIA -STD-0015** WG 1 will investigate the current status of the Ball Grid Array Re-balling standard and the possibility of WG 1 to propose a PoW to create a new TS